WIRE BONDING APPARATUS AND WIRE BONDING METHOD

ABSTRACT OF THE DISCLOSURE

Provided is a wire bonding apparatus including: a wire cutting unit configured to cut a wire by bonding the wire using a capillary and then moving the capillary and a first clamper upward while the first clamper remains closed; and a wire extending unit configured to extend a tail wire from a tip end of the capillary by moving the capillary upward and then moving the capillary and the first clamper upward in a state in which the first clamper is opened and a second clamper is closed. The wire bonding apparatus having such a structure effectively prevents the wire from falling out and bending.